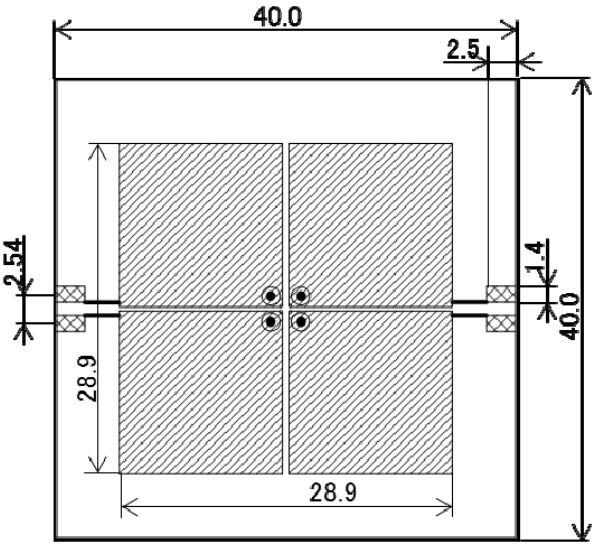
● WLP-4-01 Power Dissipation

Power dissipation data for the WLP-4-01 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition	: Mount on a board
Ambient	: Natural convection
Soldering	: Lead (Pb) free
Board Dimensions	: 40 x 40 mm (1600mm^2)
Board Structure	: 1st Meter layer about 50% 2nd Inner Metal layer about 50% 3rd Inner Metal layer about 50% 4th Metal layer about 50% 4 separations is each layer connected to each pin
Material	: Glass Epoxy (FR-4)
Thickness	: 1.6 mm
Through-hole	: 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tj max = 125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	660	151.52
85	264